Semiconductor Device Type:         ML         (8EX) 016         QFN 4x4x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				JEDEC 97 Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	30.70	(mg) Total	Mold Compound	% ot Total Weight	70.58
Silica, fused	60676-86-0	Mold Compound	63.522	27.632	635.220		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	3,423	1.489	34.231		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	3.423	1,489	34,231		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.212	0.092	2,117		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	23.308	10.139	233,082			Total	100.00	
Iron	7439-89-6	Lead Frame	0.562	0.245	5,621	10.41	(mg) Total	Lead Frame	% of Total Weight	23.92
Zinc	7440-66-6	Lead Frame	0.030	0.013	299		Copper	7440-50-8	97.44	
Phosphorous	7723-14-0	Lead Frame	0.020	0.009	197		Iron	7439-89-6	2.35	
Silver	7440-22-4	Die Attach	0.560	0.244	5,600		Zinc	7440-66-6	0.13	
Acrylate resins	Trade Secret	Die Attach	0.140	0.061	1,400		Phosphorous	7723-14-0	0.08	
Silicon	7440-21-3	Chip (Die)	3.300	1.436	33,000			Total	100.00	
Gold	7440-57-5	Wire Bond	0.250	0.109	2,500	0.30	(mg) Total	Die Attach	% of Total Weight	0.70
Nickel	7440-02-0	Plating on external leads (pins)	1.125	0.489	11,250		Silver	7440-22-4	80.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.063	0.027	625		Acrylate resins	Trade Secret	20.00	
Gold	7440-57-5	Plating on external leads (pins)	0.063	0.027	625		р <u> </u>	Total	100.00	
		TOTAL	S: 100.000	43.500	1,000,000	1.44	Total (mg)	Chip (Die)	% of Total Weight	3.30
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his semiconductor device and its homogenous materials o 015) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex	comply with EU Directives	g Total Mass :: 2002/95/EC (27 January 2003) & Directive 2011/6	/EU (08 June 2011) a	nd 2015/863/E	U (31 March		Doped Silicon	7440-21-3 Total	100.00 100.00	
his semiconductor device and its homogenous materials o 015) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex ompliance with the above EU Directives has been verified a chemical substance is absent from the list above, the ch	comply with EU Directives xemption (zero) via internal design contro	: 2002/95/EC (27 January 2003) & Directive 2011/6 ols, supplier declarations, and /or analytical test dat	a.			0.11	(mg) Total			0.25
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